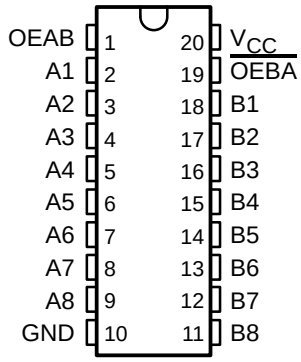
# THE DATASHEET OF

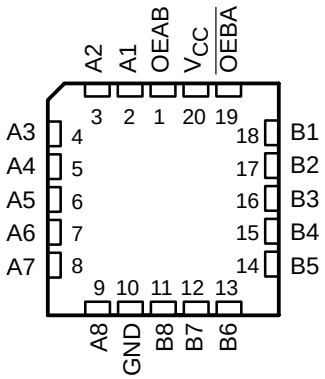
# SN74HC623DWRE4

- **Wide Operating Voltage Range of 2 V to 6 V**
- **High-Current 3-State Outputs Can Drive Up To 15 LSTTL Loads**
- **Low Power Consumption, 80-μA Max $I_{CC}$**
- **Typical $t_{pd}$ = 8 ns**
- **±6-mA Output Drive at 5 V**
- **Low Input Current of 1 μA Max**
- **Lock Bus-Latch Capability**
- **True Logic**

**SN54HC623 . . . J OR W PACKAGE**
**SN74HC623 . . . DW, N, OR NS PACKAGE**
**(TOP VIEW)**




**SN54HC623 . . . FK PACKAGE**
**(TOP VIEW)**




## description/ordering information

These octal bus transceivers are designed for asynchronous two-way communication between data buses. The control-function implementation allows for maximum flexibility in timing.

The ’HC623 devices allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending upon the logic levels at the output-enable (OEAB and $\overline{\text{OEBA}}$) inputs.

OEAB and $\overline{\text{OEBA}}$ disable the device so that the buses are effectively isolated. The dual-enable configuration gives the transceivers the capability to store data by simultaneously enabling OEAB and $\overline{\text{OEBA}}$. Each output reinforces its input in this transceiver configuration. When both OEAB and $\overline{\text{OEBA}}$ are enabled and all other data sources to the two sets of bus lines are in the high-impedance state, both sets of bus lines (16 total) remain at their last states. The 8-bit codes appearing on the two sets of buses are identical.

**ORDERING INFORMATION**

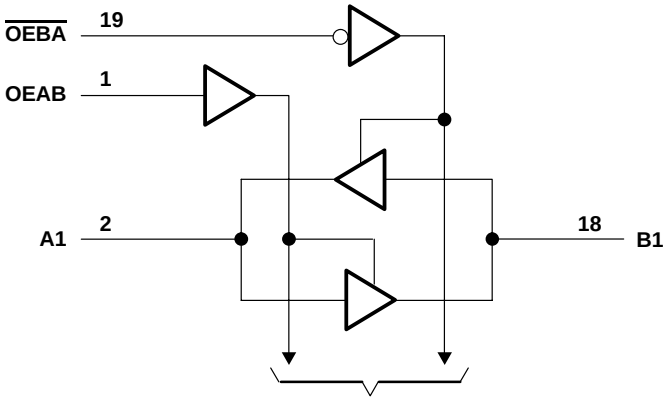
| $T_A$ | PACKAGE† | | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|---|---|---|---|---|
| –40°C to 85°C | PDIP – N | Tube | SN74HC623N | SN74HC623N |
| | SOIC – DW | Tube | SN74HC623DW | HC623 |
| | | Tape and reel | SN74HC623DWR | |
| | SOP – NS | Tape and reel | SN74HC623NSR | HC623 |
| –55°C to 125°C | CDIP – J | Tube | SNJ54HC623J | SNJ54HC623J |
| | CFP – W | Tube | SNJ54HC623W | SNJ54HC623W |
| | LCCC – FK | Tube | SNJ54HC623FK | SNJ54HC623FK |

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

**FUNCTION TABLE**

| INPUTS | | OPERATION |
|---|---|---|
| $\overline{OEBA}$ | OEAB | |
| L | L | B data to A bus |
| H | H | A data to B bus |
| H | L | Isolation |
| L | H | B data to A bus, A data to B bus |

## logic diagram (positive logic)




## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$ . . . . . –0.5 V to 7 V
Input clamp current, $I_{IK}$ ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1) . . . . . ±20 mA
Output clamp current, $I_{OK}$ ($V_O < 0$ or $V_O > V_{CC}$) (see Note 1) . . . . . ±20 mA
Continuous output current, $I_O$ ($V_O = 0$ to $V_{CC}$) . . . . . ±35 mA
Continuous current through $V_{CC}$ or GND . . . . . ±70 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): DW package . . . . . 58°C/W
N package . . . . . 69°C/W
NS package . . . . . 60°C/W
Storage temperature range, $T_{stg}$ . . . . . –65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

## recommended operating conditions (see Note 3)

| | | | SN54HC623 | | | SN74HC623 | | | UNIT |
|---|---|---|---|---|---|---|---|---|---|
| | | | MIN | NOM | MAX | MIN | NOM | MAX | |
| $V_{CC}$ | Supply voltage | | 2 | 5 | 6 | 2 | 5 | 6 | V |
| $V_{IH}$ | High-level input voltage | $V_{CC}$ = 2 V | 1.5 | | | 1.5 | | | V |
| | | $V_{CC}$ = 4.5 V | 3.15 | | | 3.15 | | | |
| | | $V_{CC}$ = 6 V | 4.2 | | | 4.2 | | | |
| $V_{IL}$ | Low-level input voltage | $V_{CC}$ = 2 V | | | 0.5 | | | 0.5 | V |
| | | $V_{CC}$ = 4.5 V | | | 1.35 | | | 1.35 | |
| | | $V_{CC}$ = 6 V | | | 1.8 | | | 1.8 | |
| $V_I$ | Input voltage | | 0 | | $V_{CC}$ | 0 | | $V_{CC}$ | V |
| $V_O$ | Output voltage | | 0 | | $V_{CC}$ | 0 | | $V_{CC}$ | V |
| $\Delta t/\Delta v$ | Input transition rise/fall time | $V_{CC}$ = 2 V | | | 1000 | | | 1000 | ns |
| | | $V_{CC}$ = 4.5 V | | | 500 | | | 500 | |
| | | $V_{CC}$ = 6 V | | | 400 | | | 400 | |
| $T_A$ | Operating free-air temperature | | –55 | | 125 | –40 | | 85 | °C |

NOTE 3: All unused inputs of the device must be held at $V_{CC}$ or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | | $V_{CC}$ | $T_A$ = 25°C | | | SN54HC623 | | SN74HC623 | | UNIT |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| | | | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| $V_{OH}$ | | $V_I$ = $V_{IH}$ or $V_{IL}$ | $I_{OH}$ = –20 μA | 2 V | 1.9 | 1.998 | | 1.9 | | 1.9 | | V |
| | | | | 4.5 V | 4.4 | 4.499 | | 4.4 | | 4.4 | | |
| | | | | 6 V | 5.9 | 5.999 | | 5.9 | | 5.9 | | |
| | | | $I_{OH}$ = –6 mA | 4.5 V | 3.98 | 4.3 | | 3.7 | | 3.84 | | |
| | | | $I_{OH}$ = –7.8 mA | 6 V | 5.48 | 5.8 | | 5.2 | | 5.34 | | |
| $V_{OL}$ | | $V_I$ = $V_{IH}$ or $V_{IL}$ | $I_{OL}$ = 20 μA | 2 V | | 0.002 | 0.1 | | 0.1 | | 0.1 | V |
| | | | | 4.5 V | | 0.001 | 0.1 | | 0.1 | | 0.1 | |
| | | | | 6 V | | 0.001 | 0.1 | | 0.1 | | 0.1 | |
| | | | $I_{OL}$ = 6 mA | 4.5 V | | 0.17 | 0.26 | | 0.4 | | 0.33 | |
| | | | $I_{OL}$ = 7.8 mA | 6 V | | 0.15 | 0.26 | | 0.4 | | 0.33 | |
| $I_I$ | $\overline{OEAB}$ or $\overline{OEBA}$ | $V_I$ = $V_{CC}$ or 0 | | 6 V | | ±0.1 | ±100 | | ±1000 | | ±1000 | nA |
| $I_{OZ}$ | A or B | $V_O$ = $V_{CC}$ or 0 | | 6 V | | ±0.01 | ±0.5 | | ±10 | | ±5 | μA |
| $I_{CC}$ | | $V_I$ = $V_{CC}$ or 0, | $I_O$ = 0 | 6 V | | | 8 | | 160 | | 80 | μA |
| $C_i$ | $\overline{OEAB}$ or $\overline{OEBA}$ | | | 2 V to 6 V | | 3 | 10 | | 10 | | 10 | pF |

### switching characteristics over recommended operating free-air temperature range, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | $V_{CC}$ | $T_A$ = 25°C | | | SN54HC623 | | SN74HC623 | | UNIT |
|---|---|---|---|---|---|---|---|---|---|---|---|
| | | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| $t_{pd}$ | A or B | B or A | 2 V | | 29 | 105 | | 160 | | 130 | ns |
| | | | 4.5 V | | 10 | 21 | | 32 | | 26 | |
| | | | 6 V | | 8 | 18 | | 27 | | 22 | |
| $t_{en}$ | $\overline{OEBA}$ | A | 2 V | | 112 | 210 | | 315 | | 265 | ns |
| | | | 4.5 V | | 27 | 42 | | 63 | | 53 | |
| | | | 6 V | | 20 | 36 | | 54 | | 45 | |
| $t_{dis}$ | $\overline{OEBA}$ | A | 2 V | | 40 | 150 | | 225 | | 190 | ns |
| | | | 4.5 V | | 18 | 30 | | 45 | | 38 | |
| | | | 6 V | | 16 | 26 | | 38 | | 32 | |
| $t_{en}$ | OEAB | B | 2 V | | 112 | 210 | | 315 | | 265 | ns |
| | | | 4.5 V | | 27 | 42 | | 63 | | 53 | |
| | | | 6 V | | 20 | 36 | | 54 | | 45 | |
| $t_{dis}$ | OEAB | B | 2 V | | 40 | 150 | | 225 | | 190 | ns |
| | | | 4.5 V | | 18 | 30 | | 45 | | 38 | |
| | | | 6 V | | 16 | 26 | | 38 | | 32 | |
| $t_t$ | | A or B | 2 V | | 20 | 60 | | 90 | | 75 | ns |
| | | | 4.5 V | | 8 | 12 | | 18 | | 15 | |
| | | | 6 V | | 6 | 10 | | 15 | | 13 | |



### switching characteristics over recommended operating free-air temperature range, $C_L$ = 150 pF (unless otherwise noted) (see Figure 1)

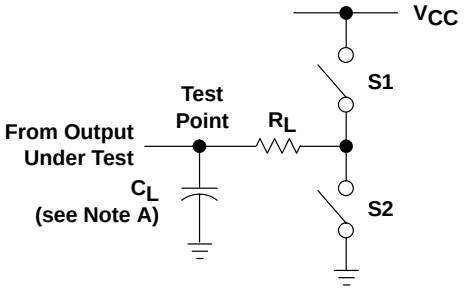
| PARAMETER | FROM (INPUT) | TO (OUTPUT) | $V_{CC}$ | $T_A$ = 25°C | | | SN54HC623 | | SN74HC623 | | UNIT |
|---|---|---|---|---|---|---|---|---|---|---|---|
| | | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| $t_{pd}$ | A or B | B or A | 2 V | | 44 | 135 | | 200 | | 170 | ns |
| | | | 4.5 V | | 14 | 27 | | 40 | | 34 | |
| | | | 6 V | | 11 | 23 | | 34 | | 29 | |
| $t_{en}$ | $\overline{OEBA}$ | A | 2 V | | 130 | 270 | | 405 | | 335 | ns |
| | | | 4.5 V | | 31 | 54 | | 81 | | 67 | |
| | | | 6 V | | 23 | 46 | | 69 | | 56 | |
| | OEAB | B | 2 V | | 130 | 270 | | 405 | | 335 | ns |
| | | | 4.5 V | | 31 | 54 | | 81 | | 67 | |
| | | | 6 V | | 23 | 46 | | 69 | | 56 | |
| $t_t$ | | A or B | 2 V | | 45 | 210 | | 315 | | 265 | ns |
| | | | 4.5 V | | 17 | 42 | | 63 | | 53 | |
| | | | 6 V | | 13 | 36 | | 53 | | 45 | |



### operating characteristics, $T_A$ = 25°C

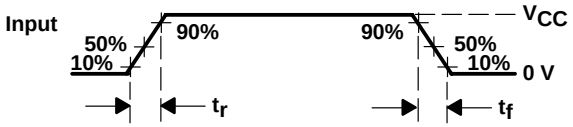
| PARAMETER | | TEST CONDITIONS | TYP | UNIT |
|---|---|---|---|---|
| $C_{pd}$ | Power dissipation capacitance per transceiver | No load | 40 | pF |

## PARAMETER MEASUREMENT INFORMATION

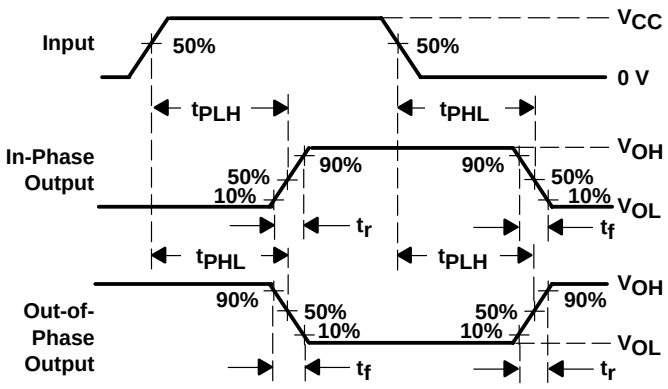



LOAD CIRCUIT

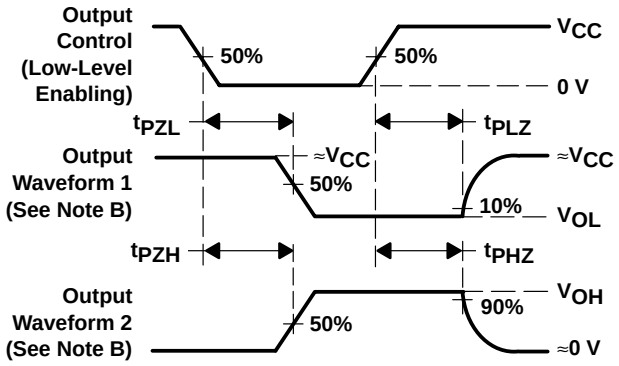
| PARAMETER | | $R_L$ | $C_L$ | S1 | S2 |
|---|---|---|---|---|---|
| $t_{en}$ | $t_{PZH}$ | 1 kΩ | 50 pF or 150 pF | Open | Closed |
| | $t_{PZL}$ | | | Closed | Open |
| $t_{dis}$ | $t_{PHZ}$ | 1 kΩ | 50 pF | Open | Closed |
| | $t_{PLZ}$ | | | Closed | Open |
| $t_{pd}$ or $t_t$ | | –– | 50 pF or 150 pF | Open | Open |




VOLTAGE WAVEFORM
INPUT RISE AND FALL TIMES




VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES




VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES FOR 3-STATE OUTPUTS

NOTES: A. $C_L$ includes probe and test-fixture capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, $Z_O$ = 50 Ω, $t_r$ = 6 ns, $t_f$ = 6 ns.
D. The outputs are measured one at a time with one input transition per measurement.
E. $t_{PLZ}$ and $t_{PHZ}$ are the same as $t_{dis}$.
F. $t_{PZL}$ and $t_{PZH}$ are the same as $t_{en}$.
G. $t_{PLH}$ and $t_{PHL}$ are the same as $t_{pd}$.

**Figure 1. Load Circuit and Voltage Waveforms**

## PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|---|---|---|---|---|---|---|---|---|---|---|---|
| SN74HC623DW | ACTIVE | SOIC | DW | 20 | 25 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HC623 | Samples |
| SN74HC623N | ACTIVE | PDIP | N | 20 | 20 | RoHS & Non-Green | NIPDAU | N / A for Pkg Type | -40 to 85 | SN74HC623N | Samples |
| SN74HC623NSR | ACTIVE | SO | NS | 20 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HC623 | Samples |

(1) The marketing status values are defined as follows:
**ACTIVE:** Product device recommended for new designs.
**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.
**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

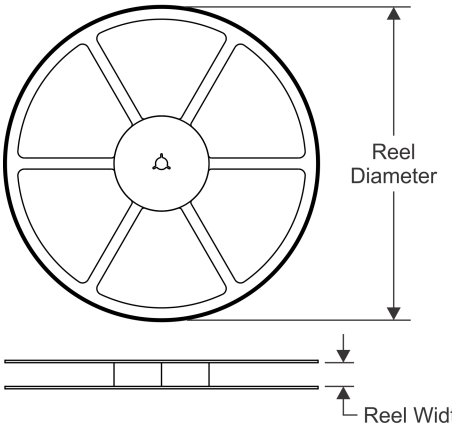
(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

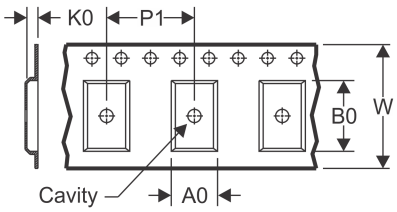
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

## TAPE AND REEL INFORMATION

**REEL DIMENSIONS**

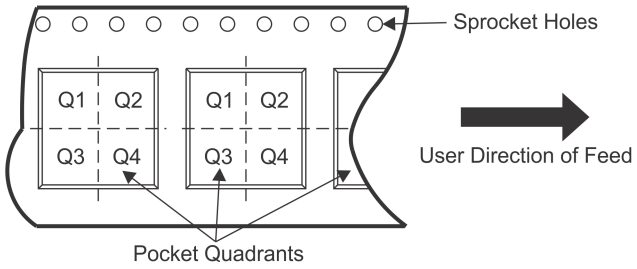



**TAPE DIMENSIONS**




| | |
|---|---|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

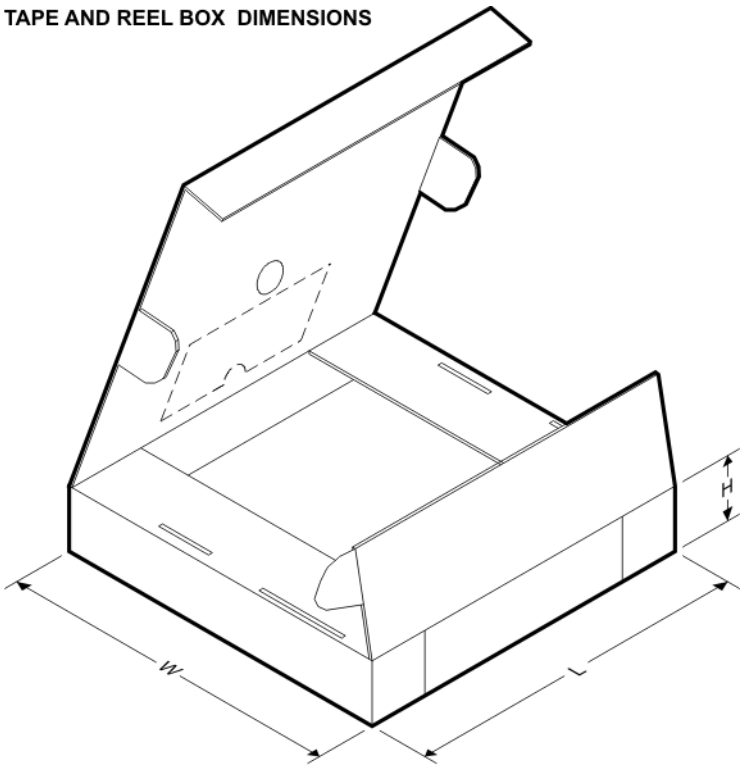
**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**




*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| SN74HC623NSR | SO | NS | 20 | 2000 | 330.0 | 24.4 | 8.4 | 13.0 | 2.5 | 12.0 | 24.0 | Q1 |

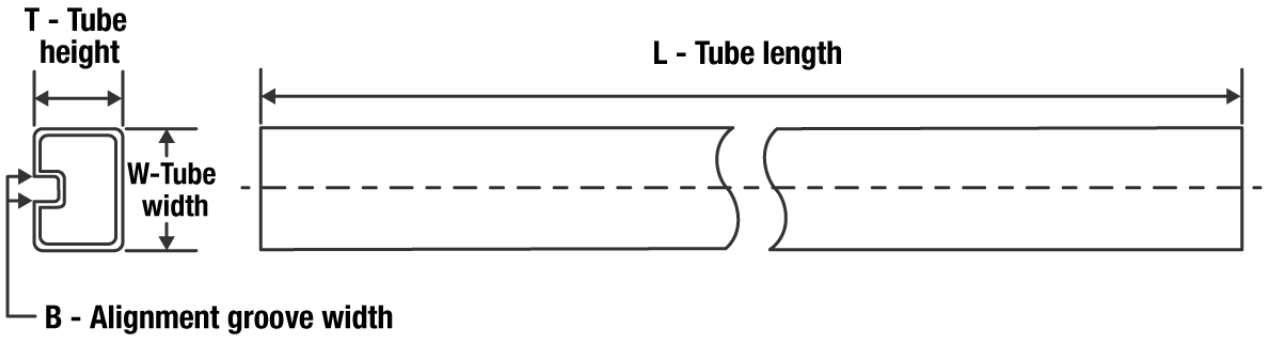
TAPE AND REEL BOX DIMENSIONS




*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---|---|---|---|---|---|---|---|
| SN74HC623NSR | SO | NS | 20 | 2000 | 367.0 | 367.0 | 45.0 |

## TUBE



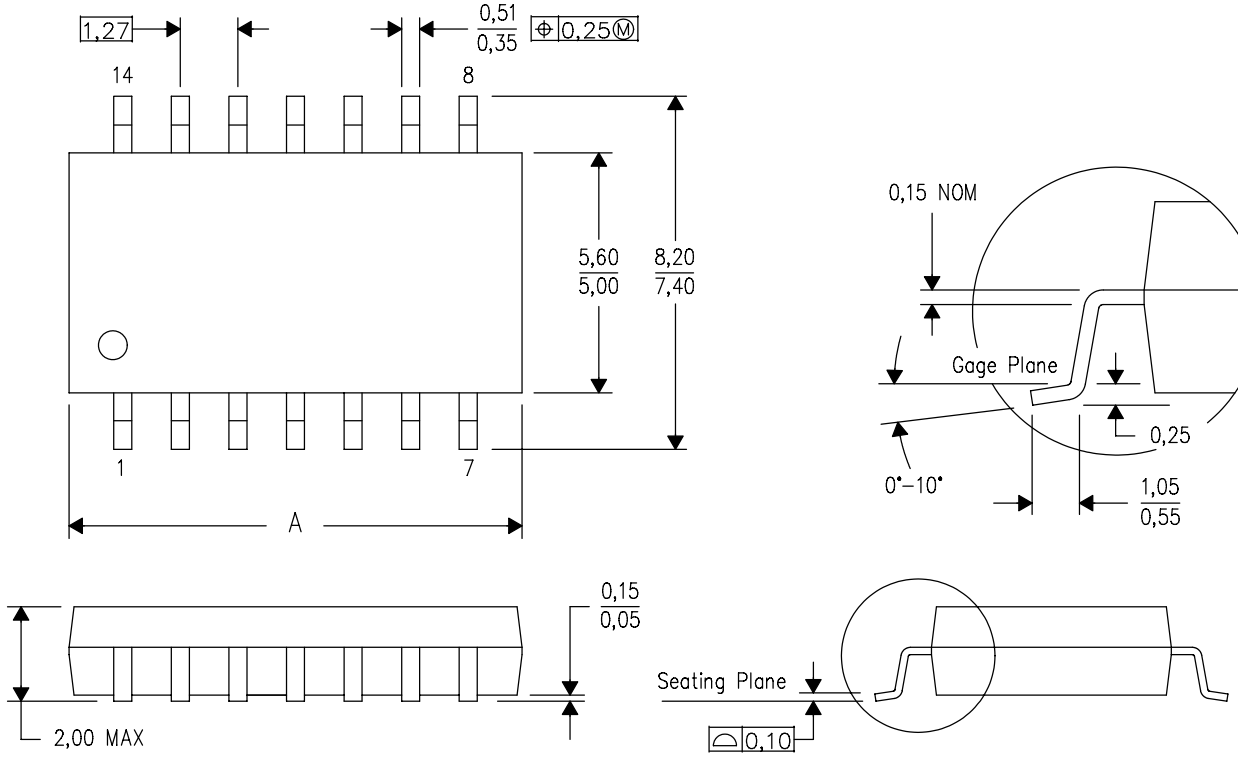

*All dimensions are nominal

| Device | Package Name | Package Type | Pins | SPQ | L (mm) | W (mm) | T (µm) | B (mm) |
|---|---|---|---|---|---|---|---|---|
| SN74HC623DW | DW | SOIC | 20 | 25 | 507 | 12.83 | 5080 | 6.6 |
| SN74HC623N | N | PDIP | 20 | 20 | 506 | 13.97 | 11230 | 4.32 |

## MECHANICAL DATA

**NS (R-PDSO-G**)** **PLASTIC SMALL-OUTLINE PACKAGE**

**14-PINS SHOWN**




| DIM \ PINS ** | 14 | 16 | 20 | 24 |
|---|---|---|---|---|
| A MAX | 10,50 | 10,50 | 12,90 | 15,30 |
| A MIN | 9,90 | 9,90 | 12,30 | 14,70 |

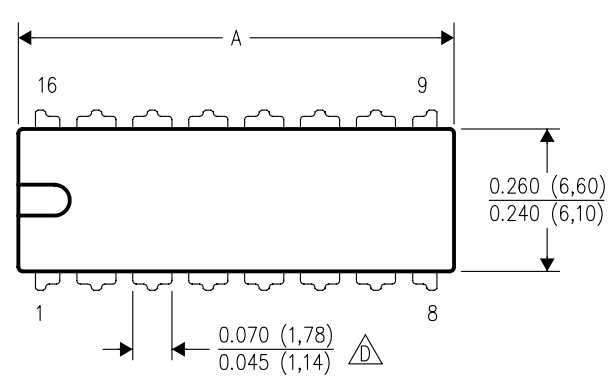
4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

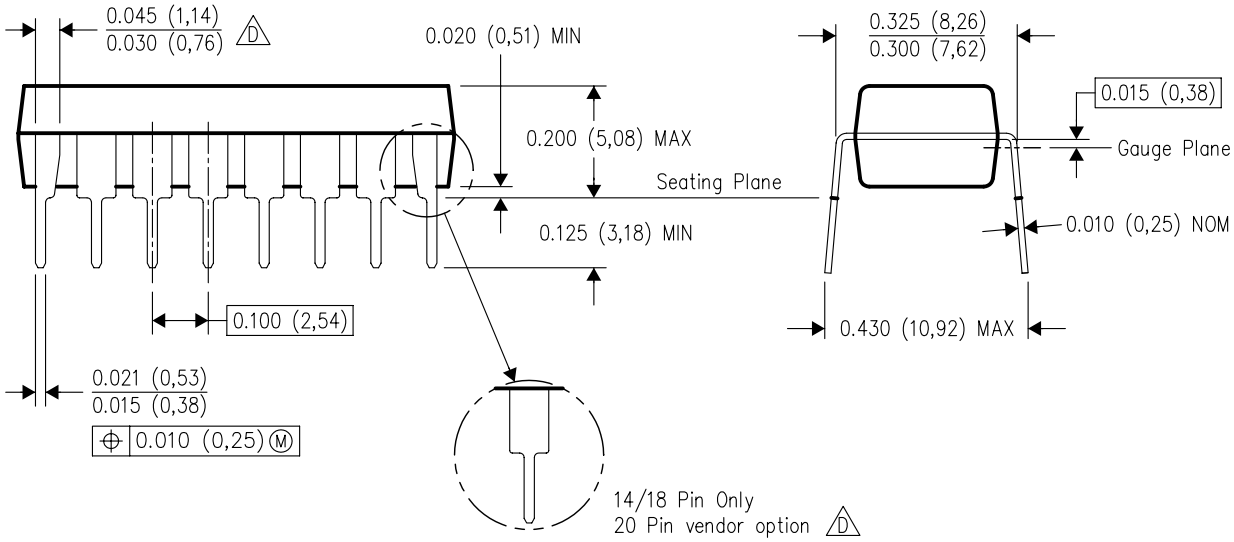
## N (R–PDIP–T**)

## PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN




| DIM \ PINS ** | 14 | 16 | 18 | 20 |
|---|---|---|---|---|
| A MAX | 0.775 (19,69) | 0.775 (19,69) | 0.920 (23,37) | 1.060 (26,92) |
| A MIN | 0.745 (18,92) | 0.745 (18,92) | 0.850 (21,59) | 0.940 (23,88) |
| MS–001 VARIATION (C) | AA | BB | AC | AD |

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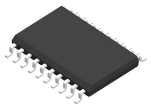
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

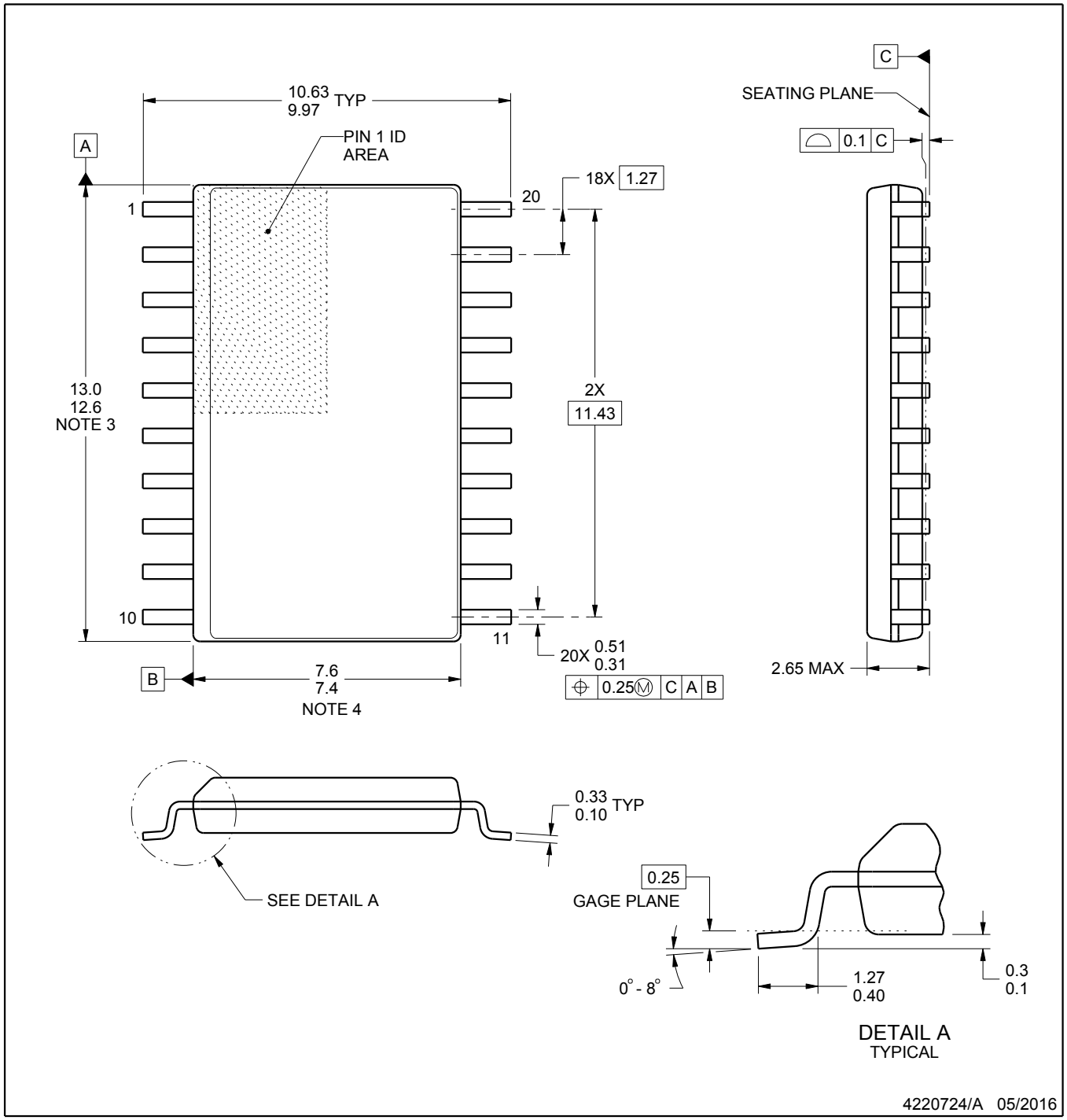


# PACKAGE OUTLINE

## DW0020A

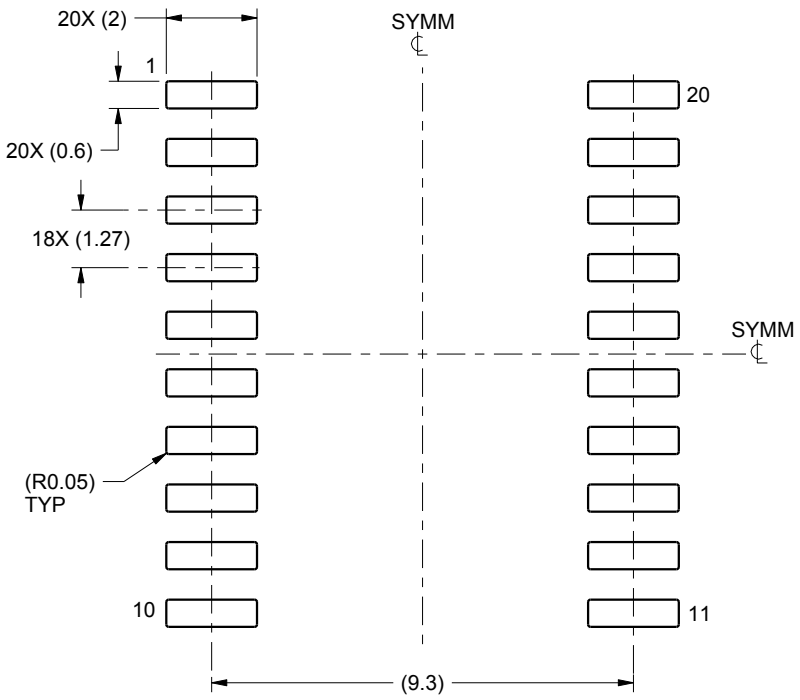
## SOIC - 2.65 mm max height

SOIC

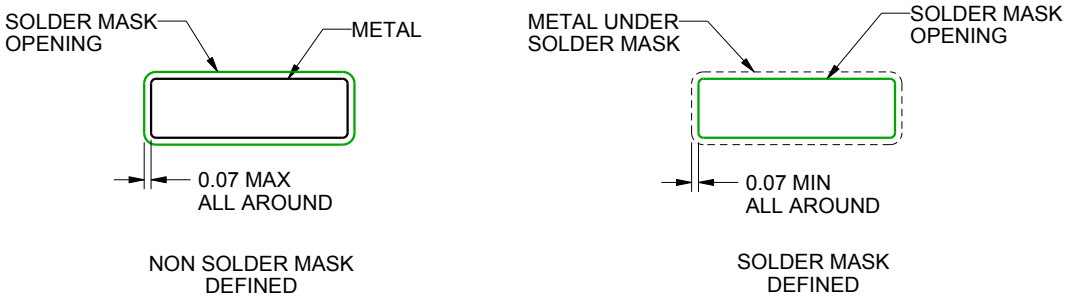



NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.




LAND PATTERN EXAMPLE
SCALE:6X




SOLDER MASK DETAILS

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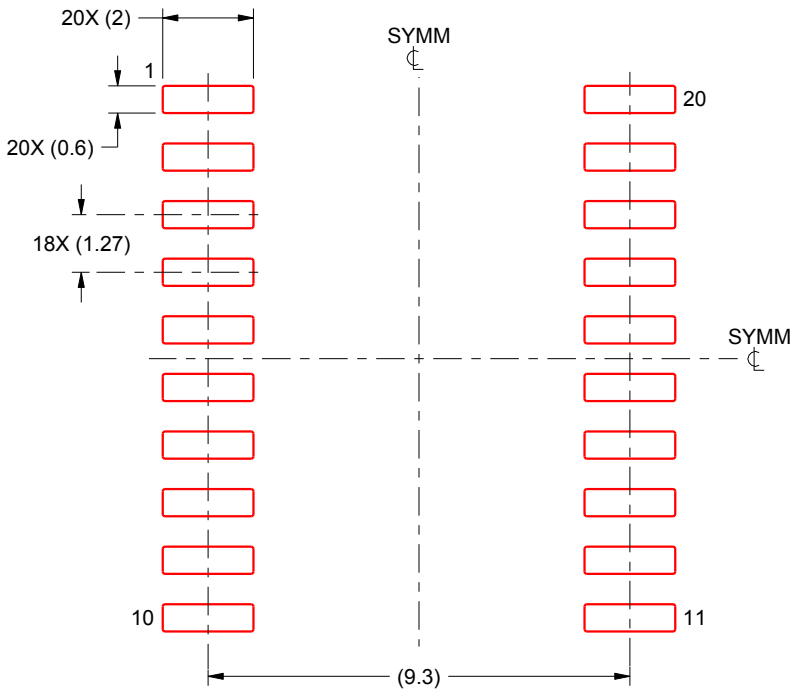
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.




SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

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NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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